

General Description

The WSF70N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF70N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

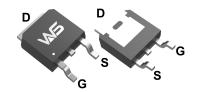
Product Summery

BV _{DSS}	R _{DSON}	I _D
100V	10mΩ	70A

Applications

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

TO-252 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter Rating		Units
V_{DS}	Drain-Source Voltage 100		V
V_{GS}	Gate-Source Voltage	±25	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	70	Α
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	35	Α
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	8.2	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	6.6	Α
I _{DM}	Pulsed Drain Current ^{2,} T _C =25°C	150	А
EAS	Avalanche Energy, Single pulse,L=0.5mH	169	mJ
I _{AS}	Avalanche Current, Single pulse,L=0.5mH	26	Α
P _D @T _C =25℃	Total Power Dissipation⁴	113	W
P _D @T _C =100°C	Total Power Dissipation ⁴	45	W
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}\mathbb{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}\mathbb{C}$

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		1.1	°C/W



Electrical Characteristics (T_J=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.096		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =30A		10	13	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} . In =250uA	2.0	3.0	4.0	٧
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS , ID -250UA		-5.5		mV/℃
	Drain Source Leakage Current	V_{DS} =80V , V_{GS} =0V , T_{J} =25 $^{\circ}$ C			1	- uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =80V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C			5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		27		S
R_g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		1.0	1.8	Ω
Q_g	Total Gate Charge (10V)			42		
Q_{gs}	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =30A		12		nC
Q_{gd}	Gate-Drain Charge			12		
T _{d(on)}	Turn-On Delay Time			19		
Tr	Rise Time	V_{DD} =50V , V_{GS} =10V , R_{G} =3 Ω ,		9		
T _{d(off)}	Turn-Off Delay Time	I _D =1A		36		ns
T _f	Fall Time			22		
C _{iss}	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		2100		
Coss	Output Capacitance			255		pF
C _{rss}	Reverse Transfer Capacitance			100		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.5mH , I _{AS} =26A	150			mJ

Diode Characteristics

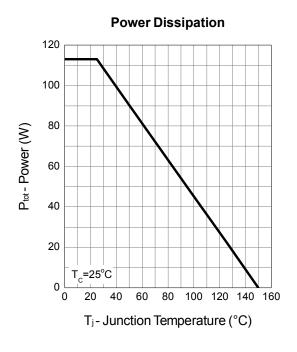
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			30	Α
I _{SM}	Pulsed Source Current ^{2,6}				60	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =15A , T _J =25℃			1.3	V
t _{rr}	Reverse Recovery Time	 IF=15A,dI/dt=100A/μs,T _J =25℃		42		nS
Qrr	Reverse Recovery Charge			90		nC

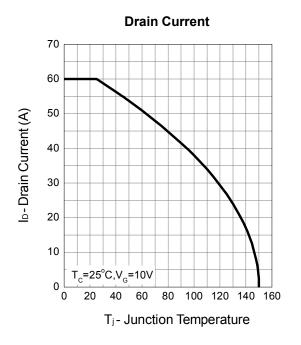
Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is V_{DS} =25V, V_{GS} =10V,L=0.5mH, I_{AS} =26A
- 4.The power dissipation is limited by 150 $^{\circ}\mathrm{C}\,$ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

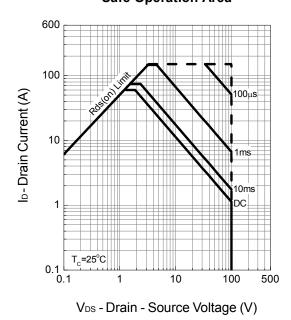


Typical Operating Characteristics

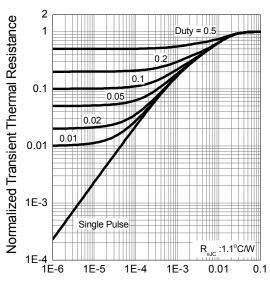




Safe Operation Area



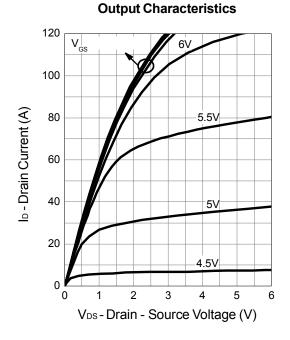
Thermal Transient Impedance



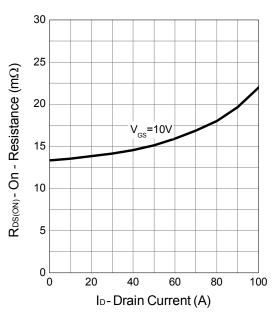
Square Wave Pulse Duration (sec)



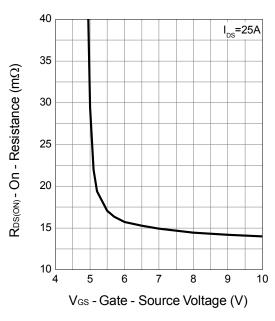
Typical Operating Characteristics (Cont.)



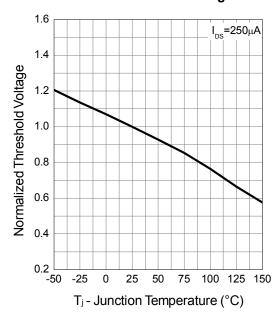
Drain-Source On Resistance



Gate-Source On Resistance



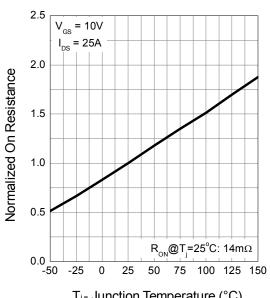
Gate Threshold Voltage



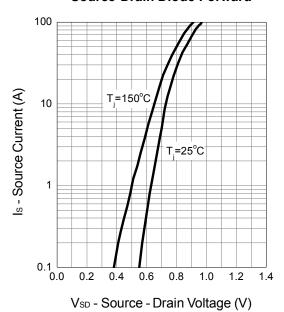


Typical Operating Characteristics (Cont.)

Drain-Source On Resistance

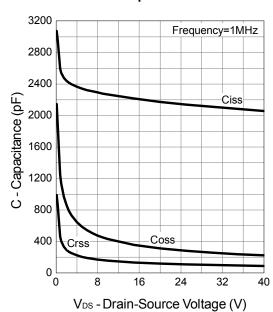


Source-Drain Diode Forward

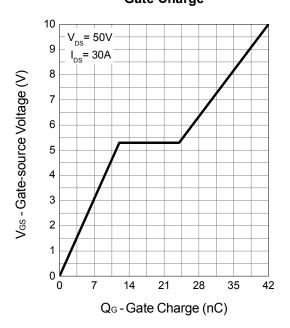


T_j- Junction Temperature (°C)

Capacitance



Gate Charge





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